

ABSTRACT OF THE DISCLOSURE

The semiconductor device is manufactured as follows.
That is, after the die pad section, on which the semiconductor
chip is mounted, the inner lead section and at least a part
5 of the outer lead section are arranged in the cavity of the
metal mold on the lead frame. Moreover, the sealing resin
is filled into the cavity of the metal mold and hardened
therein. Moreover, the sealing resin located on a surface
layer region of the outer lead section of the lead frame
10 removed.